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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Wing-Cheong Gilbert Lai et al. 09/282441	
	Filing Date: Herewith	Group: Unknown

## U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TU	4,999,160	03/12/1991	Lowrey, T.A., et al.	420	529	12/04/88
	5,192,589	03/09/1993	Sandhu, G.S.	427	255.1	09/05/91
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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## OTHER DOCUMENTS

**Examiner Initial	Including Author, Title, Date, Pertinent Pages, Etc.
TU	Fiordalice, R.W., et al., "Orientation Control of Chemical Vapor Deposition TiN Film for Barrier Applications", <u>Journal of the Electrochemical Society</u> , 143(6), pgs. 2059-2063, (June 1996)
TU	Lee, H., et al., "Study of Diffusion Barrier Performance in MOCVD TiN by Transmission Electron Microscopy", <u>Materials Research Society Symposium Proceedings</u> , 391, pgs. 205-209, (1995)
TU	Pramanik, D., et al., "Effect of Underlayer on Sputtered Aluminum Grain Structure and its Correlation with Step Coverage in Submicron Vias", 1990 <u>Proceedings Seventh International IEEE VLSI Multilevel Interconnection Conference</u> , IEEE Catalog No. 90TH0325-1, pgs. 332 - 334, (June 1990)

Examiner <u>G. G. G.</u>	Date Considered <u>6/13/03</u>
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\*Substitute Disclosure Statement Form PTO 1449

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 209; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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